



SHEET 1 OF 1

| <p style="text-align: center;">LIST OF ART CITED BY APPLICANT (PTO-1449)</p> | | | ATTY. DOCKET NO. IK-0073 | APPLN. SERIAL NO. 10/786,308 | | |
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| | | | APPLICANT(S) Ye-Yong KIM | | | |
| | | | FILING DATE February 26, 2004 | GROUP 3744 | | |
| | | | U.S. PATENT DOCUMENTS | | | |
| EXAMINER'S INITIALS | *PATENT NO. | *ISSUE DATE | *INVENTOR NAME | CLASS | SUBCLASS | FILING DATE |
| CJ | 6,351,382 B1 | 02-2002 | Nakanishi et al. | 361 | 700 | |
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| CJ | 2002/0167799 A1 | 11-2002 | Kawashima et al. | 361 | 700 | |
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| FOREIGN PATENT DOCUMENTS | | | | | | |
| EXAMINER'S INITIALS | PATENT NO. | DATE | COUNTRY | CLASS | SUBCLASS | Translation |
| CJ | CN2515800 | 10/9/02 | China (Full reference) | | | Yes <input checked="" type="checkbox"/> No <input type="checkbox"/> |
| | | | | | | |
| OTHER ART (Including Author, Title, Date, Pertinent Pages, Publisher, Place of Publication, Etc.) | | | | | | |
| CJ | David A. Reay, Heat Pipe, in AccessScience@McGraw-Hill, http://www.accessscience.com , DOI 10.1036/1097-8542.757297, May 13, 2002 | | | | | |
| CJ | Charles A. Harper, Cooling with Heat Pipes, Electronic packaging & Interconnection Handbook, pages 2.79-2.80, McGraw Hill, 1997 | | | | | |
| EXAMINER <i>CJ</i> | | | DATE CONSIDERED <i>4/7/06</i> | | | |

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